

SAMTM Data Sheet SAM-2400-1-10ps-x, λ = 2400 nm

Laser wavelength	λ = 2400 nm
High reflection band	λ = 2300 2650 nm
Absorbance	$A_0 = 1 \%$
Modulation depth	∆R = 0.6 %
Non-saturable loss	A _{ns} = 0.4 %
Saturation fluence	Φ_{sat} = 90 μ J/cm ²
Relaxation time constant	τ ~ 10 ps
Damage threshold	Φ = 1.5 mJ/cm ²
Chip area	4.0 mm x 4.0 mm; other dimensions on request
Chip thickness	620 μm
Protection	the SAM is protected with a dielectric AR layer
Reverse design	the absorber layer is illuminated through the 620 μm thick GaAs wafer
Mounting option x denotes the type of mounting as follows: x = 0 unmounted x = 12.7 g glued on a copper heat sink with 12.7 mm diameter	

x = 12.7 g	glued on a copper heat sink with 12.7 mm diameter
x = 25.4 g	glued on a copper heat sink with 25.4 mm diameter
x = 12.7 s	soldered on a copper heat sink with 12.7 mm diameter
x = 25.4 s	soldered on a copper heat sink with 25.4 mm diameter
x = 25.0 w	soldered on a water cooled copper heat sink with 25.0 mm diameter

Low intensity spectral reflectance reflectance [%] SAM 624-I wavelength [nm]



Reverse design of the SAM-2400-1-x-500fs

